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Philosophical Magazine > Volume 86, 2006 - Issue 32

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# Microstructure, indentation and work hardening of Cu/Ag multilayers

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Pages 5009-5016 | Received 20 Jan 2006, Accepted 29 Mar 2006, Published online: 19 Aug 2006

66 Cite this article

https://doi.org/10.1080/14786430600746440

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Los Alamos National Laboratory and NSERC Canada are acknowledged for financial support. The work at Harvard was supported by the Harvard Materials Research Science and Engineering Center under contract number DMR 98-09363. H.H. acknowledges support from an AlliedSignal predoctoral fellowship.

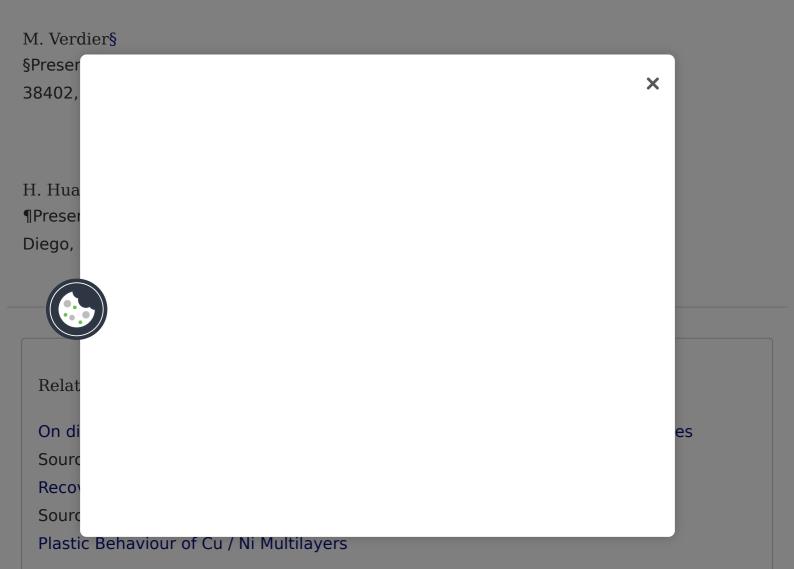
## Notes

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#### Notes on contributors



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An improved technique for determining hardness and elastic modulus using load and

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